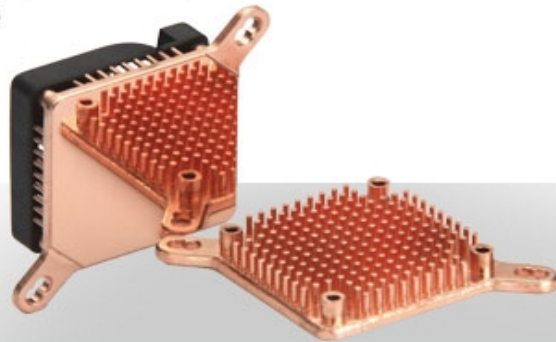


### BGA Cooler



# SLF-1

Pure Copper, Low Profile  
Less Interference



## SPECIFICATION

### COOLER

Total dimension	37*37*13.5(H)mm
Weight	51g
Rth	1.9 °C/W

### HEATSINK

Material	CU 1100
Technology	Forge
Dimension	37*37*6.6(h)mm
Base (thickness)	2.6 mm
Weight	42 g.
Finish	Redox

### FAN

Dimension	35*35*6.5(H)mm.
Bearing	One ball & one sleeve
Voltage	12 V.DC
Current	0.06 Amp
Speed	8000 R.P.M.
Air flow	4.7 CFM

### Heat source

Dimension	12*12 mm
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